

256K (32K x 8) Low-Voltage CMOS EPROM

FEATURES

- Wide voltage range 3.0V to 5.5V
- High speed performance
 - 200 ns access time available at 3.0V
- CMOS Technology for low power consumption
 - 8 mA Active current at 3.0V
 - 20 mA Active current at 5.5V
 - 100 μ A Standby current
- Factory programming available
- Auto-insertion-compatible plastic packages
- Auto ID aids automated programming
- Separate chip enable and output enable controls
- High speed "Express" programming algorithm
- Organized 32K x 8: JEDEC standard pinouts
 - 28-pin Dual-in-line package
 - 32-pin PLCC package
 - 28-pin SOIC package
 - 28-pin VSOP package
 - Tape and reel
- Data Retention > 200 years
- Available for the following temperature ranges:
 - Commercial: 0°C to +70°C
 - Industrial: -40°C to +85°C

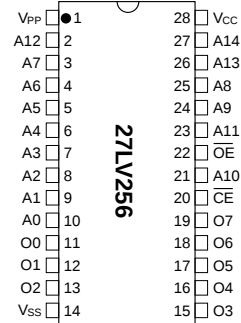
DESCRIPTION

The Microchip Technology Inc. 27LV256 is a low voltage (3.0 volt) CMOS EPROM designed for battery powered applications. The device is organized as a 32K x 8 (32K-Byte) non-volatile memory product. The 27LV256 consumes only 8 mA maximum of active current during a 3.0 volt read operation therefore improving battery performance. This device is designed for very low voltage applications where conventional 5.0 volt only EPROMS can not be used. Accessing individual bytes from an address transition or from power-up (chip enable pin going low) is accomplished in less than 200 ns at 3.0V. This device allows systems designers the ability to use low voltage non-volatile memory with today's low voltage microprocessors and peripherals in battery powered applications.

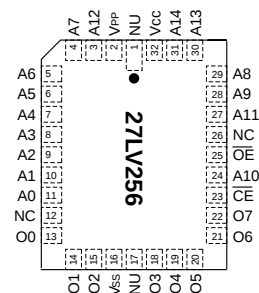
A complete family of packages is offered to provide the most flexibility in applications. For surface mount applications, PLCC, VSOP or SOIC packaging is available. Tape and reel packaging is also available for PLCC or SOIC packages.

PACKAGE TYPES

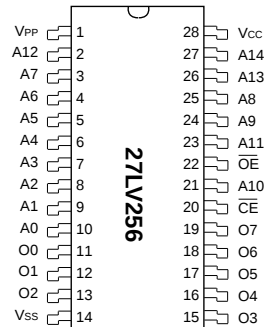
PDIP



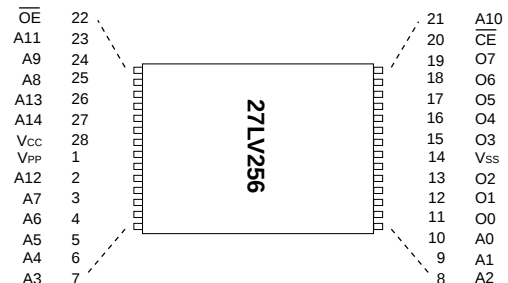
PLCC



SOIC



VSOP



1.0 ELECTRICAL CHARACTERISTICS

1.1 Maximum Ratings*

V_{CC} and input voltages w.r.t. V_{SS} -0.6V to +7.25V

V_{PP} voltage w.r.t. V_{SS} during programming -0.6V to +14V

Voltage on A9 w.r.t. V_{SS} -0.6V to +13.5V

Output voltage w.r.t. V_{SS} -0.6V to V_{CC} +1.0V

Storage temperature -65°C to +150°C

Ambient temp. with power applied -65°C to +125°C

*Notice: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 1-1: PIN FUNCTION TABLE

Name	Function
A0-A14	Address Inputs
$\overline{CE}$	Chip Enable
$\overline{OE}$	Output Enable
V _{PP}	Programming Voltage
O0 - O7	Data Output
V _{CC}	+5V or +3V Power Supply
V _{SS}	Ground
NC	No Connection; No Internal Connection
NU	Not Used; No External Connection Is Allowed

TABLE 1-2: READ OPERATION DC CHARACTERISTICS

V _{CC} = +5V ±10% or 3.0V where indicated							
				Commercial: Tamb = 0°C to +70°C			
				Industrial: Tamb = -40°C to +85°C			
Parameter	Part*	Status	Symbol	Min.	Max.	Units	Conditions
Input Voltages	all	Logic "1"	V _{IH}	2.0	V _{CC} +1	V	
		Logic "0"	V _{IL}	-0.5	0.8	V	
Input Leakage	all		I _{LI}	-10	10	μA	V _{IN} = 0 to V _{CC}
Output Voltages	all	Logic "1"	V _{OH}	2.4		V	I _{OH} = -400 μA I _{OL} = 2.1 mA
		Logic "0"	V _{OL}		0.45	V	
Output Leakage	all	—	I _{LO}	-10	10	μA	V _{OUT} = 0V to V _{CC}
Input Capacitance	all	—	C _{IN}	—	6	pF	V _{IN} = 0V; Tamb = 25°C; f = 1 MHz
Output Capacitance	all	—	C _{OUT}	—	12	pF	V _{OUT} = 0V; Tamb = 25°C; f = 1 MHz
Power Supply Current, Active	C	TTL input	I _{CC1}	—	20 @ 5.0V	mA	V _{CC} = 5.5V; V _{PP} = V _{CC} f = 1 MHz; $\overline{OE} = \overline{CE} = V_{IL}$; I _{OUT} = 0 mA; V _{IL} = -0.1 to 0.8V; V _{IH} = 2.0 to V _{CC} ; Note 1
	I	TTL input	I _{CC2}	—	8 @ 3.0V	mA	
					25 @ 5.0V	mA	
					10 @ 3.0V	mA	
Power Supply Current, Standby	C	TTL input	I _{CC(s)}	—	1 @ 3.0V	mA	$\overline{CE} = V_{CC} \pm 0.2V$
	I	TTL input			2 @ 3.0V	mA	
	all	CMOS input			100 @ 3.0V	μA	

* Parts: C=Commercial Temperature Range

I =Industrial Temperature Ranges

Note 1: Typical active current increases .75 mA per MHz up to operating frequency for all temperature ranges.

TABLE 1-3: READ OPERATION AC CHARACTERISTICS

AC Testing Waveform: $V_{IH} = 2.4V$ and $V_{IL} = 0.45V$; $V_{OH} = 2.0V$ $V_{OL} = 0.8V$ Output Load: 1 TTL Load + 100 pF Input Rise and Fall Times: 10 ns Ambient Temperature: Commercial: $T_{amb} = 0^{\circ}C$ to $+70^{\circ}C$ Industrial: $T_{amb} = -40^{\circ}C$ to $+85^{\circ}C$									
Parameter	Sym	27HC256-20		27HC256-25		27HC256-30		Units	Conditions
		Min	Max	Min	Max	Min	Max		
Address to Output Delay	t_{ACC}	—	200	—	250	—	300	ns	$\overline{CE} = \overline{OE} = V_{IL}$
$\overline{CE}$ to Output Delay	t_{CE}	—	200	—	250	—	300	ns	$\overline{OE} = V_{IL}$
$\overline{OE}$ to Output Delay	t_{OE}	—	100	—	125	—	125	ns	$\overline{CE} = V_{IL}$
$\overline{CE}$ or $\overline{OE}$ to O/P High Impedance	t_{OFF}	0	50	0	50	0	50	ns	
Output Hold from Address $\overline{CE}$ or $\overline{OE}$, whichever goes first	t_{OH}	0	—	0	—	0	—	ns	

FIGURE 1-1: READ WAVEFORMS

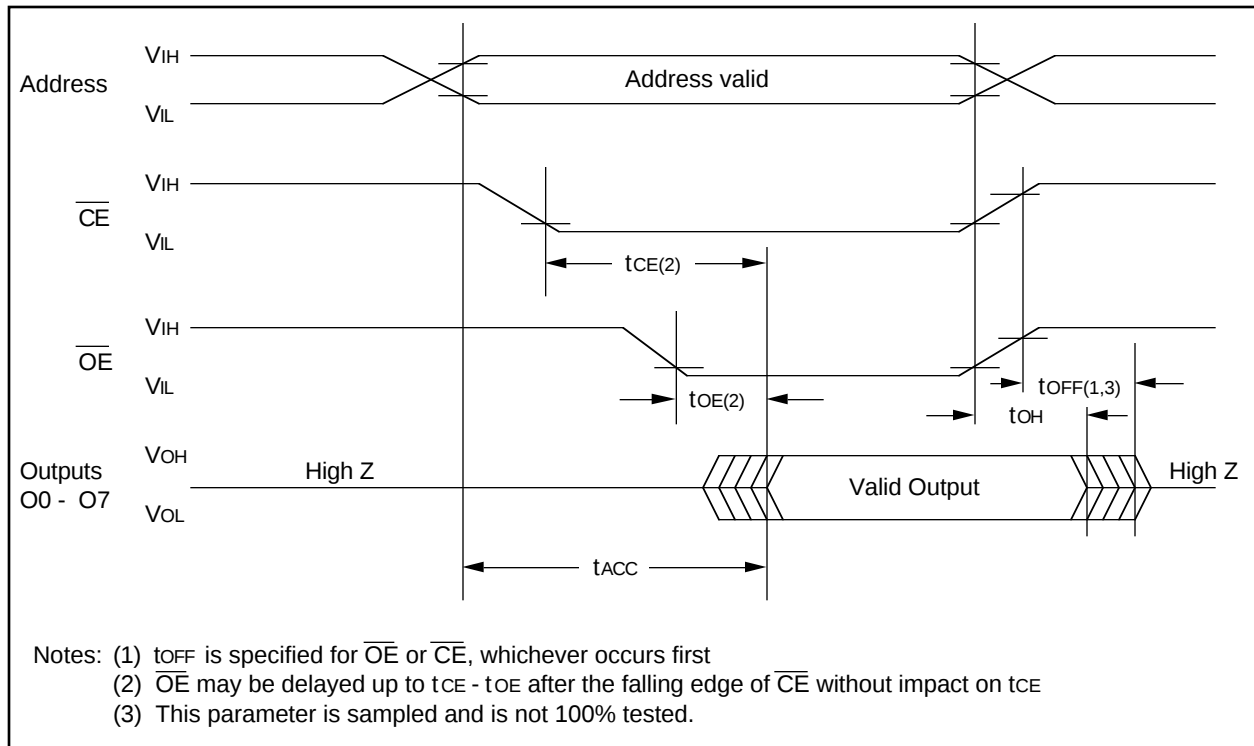


TABLE 1-4: PROGRAMMING DC CHARACTERISTICS

Ambient Temperature: Tamb = 25°C ± 5°C VCC = 6.5V ± 0.25V, VPP = 13.0V ± 0.25V						
Parameter	Status	Symbol	Min	Max.	Units	Conditions
Input Voltages	Logic"1"	VIH	2.0	VCC+1	V	
	Logic"0"	VIL	-0.1	0.8	V	
Input Leakage	—	ILI	-10	10	μA	VIN = 0V to VCC
Output Voltages	Logic"1"	VOH	2.4		V	IOH = -400 μA IOL = 2.1 mA
	Logic"0"	VOL		0.45	V	
VCC Current, program & verify	—	ICC2	—	20	mA	Note 1
VPP Current, program	—	I PP2	—	25	mA	Note 1
A9 Product Identification	—	VH	11.5	12.5	V	

Note 1: VCC must be applied simultaneously or before VPP and removed simultaneously or after VPP.

TABLE 1-5: PROGRAMMING AC CHARACTERISTICS

for Program, Program Verify and Program Inhibit Modes	AC Testing Waveform: $V_{IH}=2.4V$ and $V_{IL}=0.45V$; $V_{OH}=2.0V$; $V_{OL}=0.8V$ Output Load: 1 TLL Load + 100pF Ambient Temperature: $T_{amb}=25^{\circ}C\pm 5^{\circ}C$ $V_{CC}=6.5V\pm 0.25V$, $V_{PP}=13.0V\pm 0.25V$				
Parameter	Symbol	Min.	Max.	Units	Remarks
Address Set-Up Time	tAS	2	—	μs	
Data Set-Up Time	tDS	2	—	μs	
Data Hold Time	tDH	2	—	μs	
Address Hold Time	tAH	0	—	μs	
Float Delay (2)	tDF	0	130	ns	
Vcc Set-Up Time	tVCS	2	—	μs	
Program Pulse Width (1)	tpw	95	105	μs	100 μs typical
$\overline{CE}$ Set-Up Time	tCES	2	—	μs	
$\overline{OE}$ Set-Up Time	toES	2	—	μs	
VPP Set-Up Time	tvPS	2	—	μs	
Data Valid from $\overline{OE}$	toE	—	100	ns	

Note 1: For express algorithm, initial programming width tolerance is 100 μs ±5%.

2: This parameter is only sampled and not 100% tested. Output float is defined as the point where data is no longer driven (see timing diagram).

FIGURE 1-2: PROGRAMMING WAVEFORMS

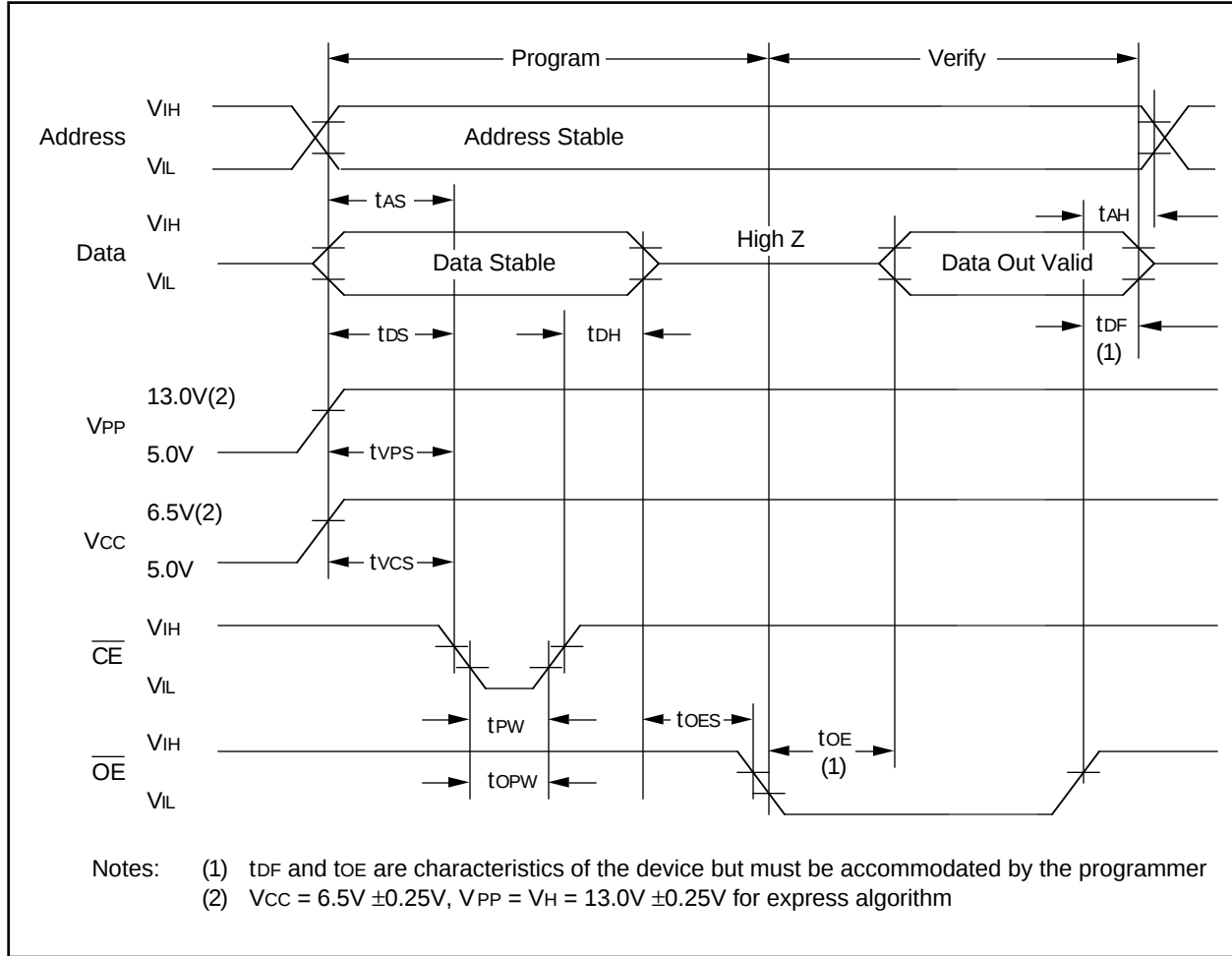


TABLE 1-6: MODES

Operation Mode	$\overline{CE}$	$\overline{OE}$	V _{PP}	A9	O0 - O7
Read	V _{IL}	V _{IL}	V _{CC}	X	DOUT
Program	V _{IL}	V _{IH}	V _H	X	DIN
Program Verify	V _{IH}	V _{IL}	V _H	X	DOUT
Program Inhibit	V _{IH}	V _{IH}	V _H	X	High Z
Standby	V _{IH}	X	V _{CC}	X	High Z
Output Disable	V _{IL}	V _{IH}	V _{CC}	X	High Z
Identity	V _{IL}	V _{IL}	V _{CC}	V _H	Identity Code

X = Don't Care

1.2 Read Mode

(See Timing Diagrams and AC Characteristics)

Read Mode is accessed when:

- the $\overline{CE}$ pin is low to power up (enable) the chip
- the $\overline{OE}$ pin is low to gate the data to the output pins

For Read operations, if the addresses are stable, the address access time (t_{ACC}) is equal to the delay from $\overline{CE}$ to output (t_{CE}). Data is transferred to the output after a delay from the falling edge of $\overline{OE}$ (t_{OE}).

1.3 Standby Mode

The standby mode is defined when the $\overline{CE}$ pin is high (V_{IH}) and a program mode is not defined. Output Disable

1.4 Output Enable

This feature eliminates bus contention in multiple bus microprocessor systems and the outputs go to a high impedance when the following condition is true:

- The $\overline{OE}$ pin is high and program mode is not defined.

1.5 Programming Mode

The Express algorithm has been developed to improve on the programming throughput times in a production environment. Up to 10 100-microsecond pulses are applied until the byte is verified. No over-programming is required. A flowchart of the express algorithm is shown in Figure 1.

Programming takes place when:

- VCC is brought to the proper voltage
- VPP is brought to the proper V_H level
- the $\overline{OE}$ pin is high
- the $\overline{CE}$ pin is low

Since the erased state is "1" in the array, programming of "0" is required. The address to be programmed is set via pins A0-A14 and the data to be programmed is presented to pins O0-O7. When data and address are stable, a low-going pulse on the $\overline{CE}$ line programs that location.

1.6 Verify

After the array has been programmed it must be verified to ensure that all the bits have been correctly programmed. This mode is entered when all of the following conditions are met:

- VCC is at the proper level
- VPP is at the proper V_H level
- the $\overline{CE}$ pin is high
- the $\overline{OE}$ line is low

1.7 Inhibit

When Programming multiple devices in parallel with different data, only $\overline{CE}$ needs to be under separate control to each device. By pulsing the $\overline{CE}$ line low on a particular device, that device will be programmed, and all other devices with $\overline{CE}$ held high will not be programmed with the data although address and data are available on their input pins.

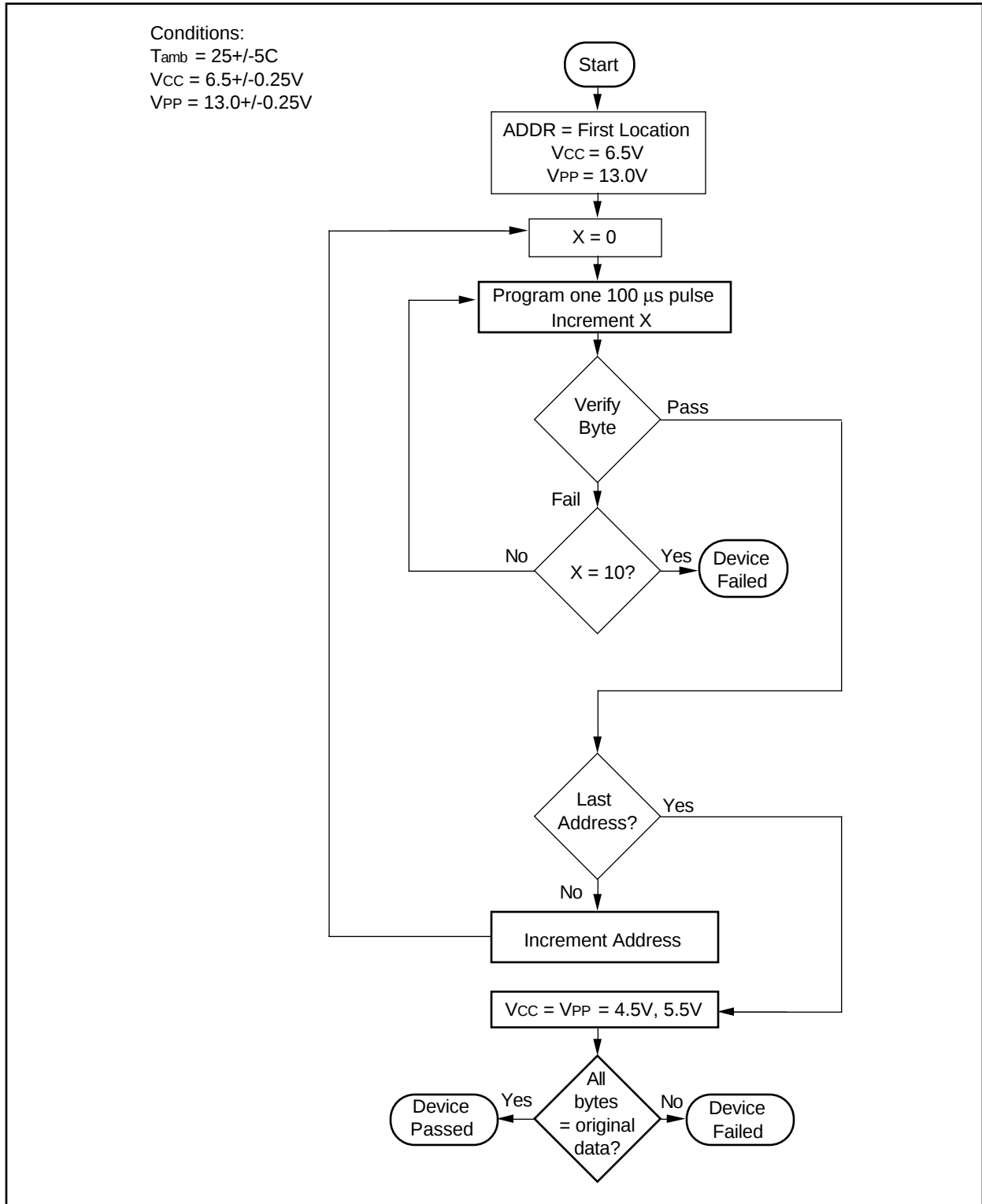
1.8 Identity Mode

In this mode specific data is outputted which identifies the manufacturer as Microchip Technology Inc. and device type. This mode is entered when Pin A9 is taken to V_H (11.5V to 12.5V). The $\overline{CE}$ and $\overline{OE}$ lines must be at V_{IL} . A0 is used to access any of the two non-erasable bytes whose data appears on O0 through O7.

Pin →	Input	Output									
Identity ↓	A0	0	0	0	0	0	0	0	0	H	e
		7	6	5	4	3	2	1	0	x	
Manufacturer	V_{IL}	0	0	1	0	1	0	0	1	29	
Device Type*	V_{IH}	1	0	0	0	1	1	0	0	8C	

* Code subject to change.

FIGURE 1-3: PROGRAMMING EXPRESS ALGORITHM



27LV256

NOTES:

NOTES:

NOTES:

27LV256

27LV256 Product Identification System

To order or to obtain information, e.g., on pricing or delivery, please use the listed part numbers, and refer to the factory or the listed sales offices.

27LV256	-	25	I	/P	
					Package:
					L = Plastic Leaded Chip Carrier
					P = Plastic DIP (600 Mil)
					SO = Plastic SOIC (300 Mil)
					VS = Very Small Outline Package (VSOP) 8X13.4mm
					Temperature Range:
					Blank = 0°C to +70°C
					I = -40°C to +85°C
					Access Time:
					20 = 200 ns
					25 = 250 ns
					30 = 300 ns (SOIC only)
					Device:
					27LV256 256K (32K x 8) Low-Voltage CMOS EPROM

WORLDWIDE SALES & SERVICE

AMERICAS

Corporate Office

Microchip Technology Inc.
2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 602 786-7200 Fax: 602 786-7277
Technical Support: 602 786-7627
Web: <http://www.microchip.com>

Atlanta

Microchip Technology Inc.
500 Sugar Mill Road, Suite 200B
Atlanta, GA 30350
Tel: 770 640-0034 Fax: 770 640-0307

Boston

Microchip Technology Inc.
5 Mount Royal Avenue
Marlborough, MA 01752
Tel: 508 480-9990 Fax: 508 480-8575

Chicago

Microchip Technology Inc.
333 Pierce Road, Suite 180
Itasca, IL 60143
Tel: 708 285-0071 Fax: 708 285-0075

Dallas

Microchip Technology Inc.
14651 Dallas Parkway, Suite 816
Dallas, TX 75240-8809
Tel: 972 991-7177 Fax: 972 991-8588

Dayton

Microchip Technology Inc.
Suite 150
Two Prestige Place
Miamisburg, OH 45342
Tel: 513 291-1654 Fax: 513 291-9175

Los Angeles

Microchip Technology Inc.
18201 Von Karman, Suite 1090
Irvine, CA 92612
Tel: 714 263-1888 Fax: 714 263-1338

New York

Microchip Technology Inc.
150 Motor Parkway, Suite 416
Hauppauge, NY 11788
Tel: 516 273-5305 Fax: 516 273-5335

San Jose

Microchip Technology Inc.
2107 North First Street, Suite 590
San Jose, CA 95131
Tel: 408 436-7950 Fax: 408 436-7955

Toronto

Microchip Technology Inc.
5925 Airport Road, Suite 200
Mississauga, Ontario L4V 1W1, Canada
Tel: 905 405-6279 Fax: 905 405-6253

ASIA/PACIFIC

China

Microchip Technology
Unit 406 of Shanghai Golden Bridge Bldg.
2077 Yan'an Road West, Hongjiao District
Shanghai, Peoples Republic of China
Tel: 86 21 6275 5700
Fax: 011 86 21 6275 5060

Hong Kong

Microchip Technology
RM 3801B, Tower Two
Metroplaza
223 Hing Fong Road
Kwai Fong, N.T. Hong Kong
Tel: 852 2 401 1200 Fax: 852 2 401 3431

India

Microchip Technology
No. 6, Legacy, Convent Road
Bangalore 560 025 India
Tel: 91 80 526 3148 Fax: 91 80 559 9840

Korea

Microchip Technology
168-1, Youngbo Bldg. 3 Floor
Samsung-Dong, Kangnam-Ku,
Seoul, Korea
Tel: 82 2 554 7200 Fax: 82 2 558 5934

Singapore

Microchip Technology
200 Middle Road
#10-03 Prime Centre
Singapore 188980
Tel: 65 334 8870 Fax: 65 334 8850

Taiwan, R.O.C

Microchip Technology
10F-1C 207
Tung Hua North Road
Taipei, Taiwan, ROC
Tel: 886 2 717 7175 Fax: 886 2 545 0139

EUROPE

United Kingdom

Arizona Microchip Technology Ltd.
Unit 6, The Courtyard
Meadow Bank, Furlong Road
Bourne End, Buckinghamshire SL8 5AJ
Tel: 44 1628 850303 Fax: 44 1628 850178

France

Arizona Microchip Technology SARL
Zone Industrielle de la Bonde
2 Rue du Buisson aux Fraises
91300 Massy - France
Tel: 33 1 69 53 63 20 Fax: 33 1 69 30 90 79

Germany

Arizona Microchip Technology GmbH
Gustav-Heinemann-Ring 125
D-81739 Muenchen, Germany
Tel: 49 89 627 144 0 Fax: 49 89 627 144 44

Italy

Arizona Microchip Technology SRL
Centro Direzionale Colleone Pas Taurus 1
Viale Colleoni 1
20041 Agrate Brianza
Milan Italy
Tel: 39 39 6899939 Fax: 39 39 689 9883

JAPAN

Microchip Technology Intl. Inc.
Benex S-1 6F
3-18-20, Shin Yokohama
Kohoku-Ku, Yokohama
Kanagawa 222 Japan
Tel: 81 45 471 6166 Fax: 81 45 471 6122

9/3/96



MICROCHIP

All rights reserved. © 1996, Microchip Technology Incorporated, USA. 9/96



Printed on recycled paper.

Information contained in this publication regarding device applications and the like is intended through suggestion only and may be superseded by updates. No representation or warranty is given and no liability is assumed by Microchip Technology Incorporated with respect to the accuracy or use of such information, or infringement of patents or other intellectual property rights arising from such use or otherwise. Use of Microchip's products as critical components in life support systems is not authorized except with express written approval by Microchip. No licenses are conveyed, implicitly or otherwise, under any intellectual property rights. The Microchip logo and name are registered trademarks of Microchip Technology Inc. All rights reserved. All other trademarks mentioned herein are the property of their respective companies.